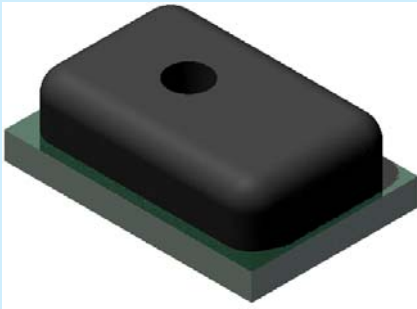


## HAT3125N4

### Ultralow Noise Microphone with Top Port and Analog Output



RoHS Compliance

Pb Free

#### Features

- Surface-mount package : 3.10mmx2.50mmx1.0mm
- Stable sensitivity over power supply range of 1.5V-3.6V.
- SNR of 59dBA.
- Sensitivity of -42dBV.
- Low current consumption of <200μA.

#### Applications

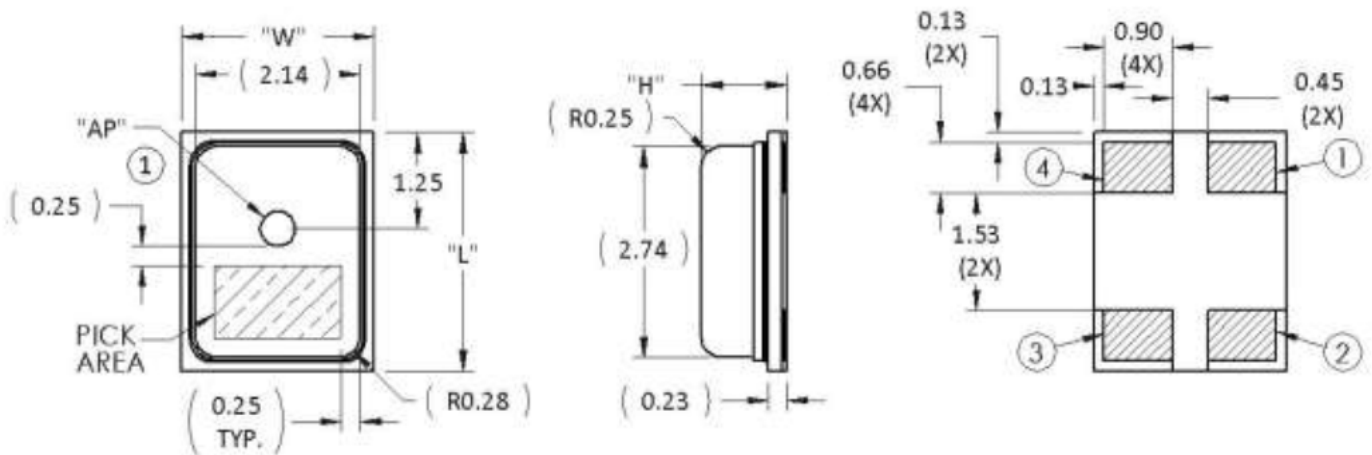
- Mobile telephones
- PDAs
- Digital video cameras
- Portable media devices with audio input

#### Description

The HAT3125N4 is a high quality, low cost, low power analog output top-ported omni-directional MEMS microphone. HAT3125N4 consists of a MEMS microphone element and an preamplifier. HAT3125N4 has a high SNR and flat wideband frequency response, resulting in natural sound with high intelligibility. Due to built-in filter, HAT3125N4 shows high immunity to EMI. The HAT3125N4 is available in a thin 3.10mm × 2.50mm × 1.0mm surface-mount package. It is reflow solder compatible with no sensitivity degradation. The HAT3125N4 is halide free.

#### MECHANICAL SPECIFICATIONNS

##### Dimension



Item	Dimension	Tolerance	Units
Length (L)	3.10	±0.10	mm
Width (W)	2.50	±0.10	mm
Height (H)	1.00	±0.10	mm
Acoustic Port (AP)	Φ0.45	±0.05	mm

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Pin #	Pin Name	Description
1	OUTPUT	Analog output signal
2	GROUND	Ground
3	GROUND	Ground
4	VDD	Power Supply

## STANDARD SPECIFICATION

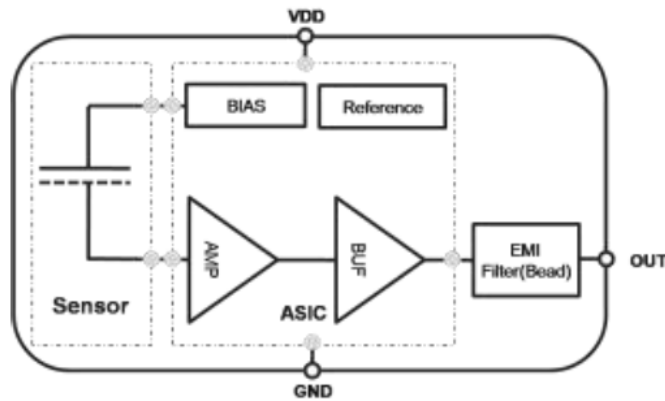
### Production Specification

(TA = +25°C, VDD = +1.8V, unless otherwise noted.)

Parameter	Symbol	Test Conditions	Min	Type	Max	Units
Directivity				Omni		
Supply Voltage	V <sub>DD</sub>		1.5		3.6	V
Current Consumption	I <sub>DD</sub>				200	μA
Sensitivity (Note)		1kHz, 94dB SPL	-45	-42	-39	dBV
Signal-to-Noise-Ratio	SNR			59		dBA
Equivalent Input Noise	EIN			34		dBASPL
Total Harmonic Distortion	THD	1kHz, 94dB SPL		0.1	0.2	%
		1kHz, 110dB SPL		0.2	0.3	
		1kHz, 120dB SPL			1	
Power Supply Rejection Ratio	PSRR	217Hz, 100mV Vp-p, square wave on VDD		65		dB
Maximum Acoustic Input		1KHz, 10% distortion	123	126		dBSPPL
Output Impedance	Z <sub>out</sub>				450	Ω
Output DC Offset				0.75		V
Output Current Limit				90		μA
Polarity				Noninverting		

Note: Base on BK sound test system.

### Functional Block Diagram



### Absolute Maximum Ratings

Parameter	Absolute Maximum Rating	Units
Supply Voltage	-0.5~4.5	V
OUT to GND	-0.3 to VDD+0.3	V
Mechanical Shock	10000	g
Vibration	Per MIL-STD-883 Method 2007, Test Condition B	
Temperature Range	-40~100	°C

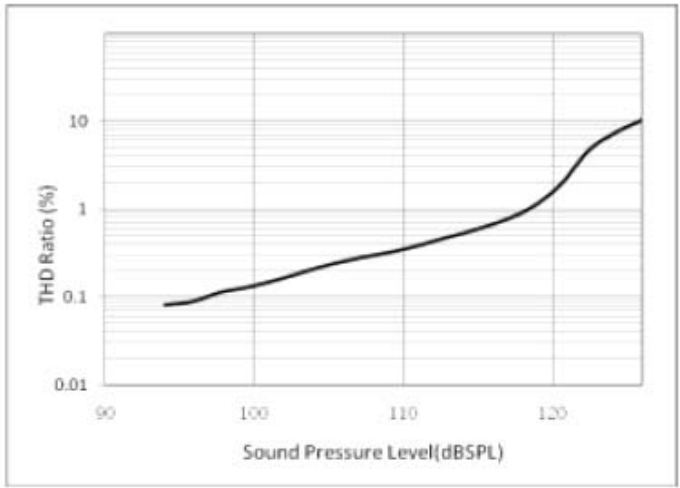
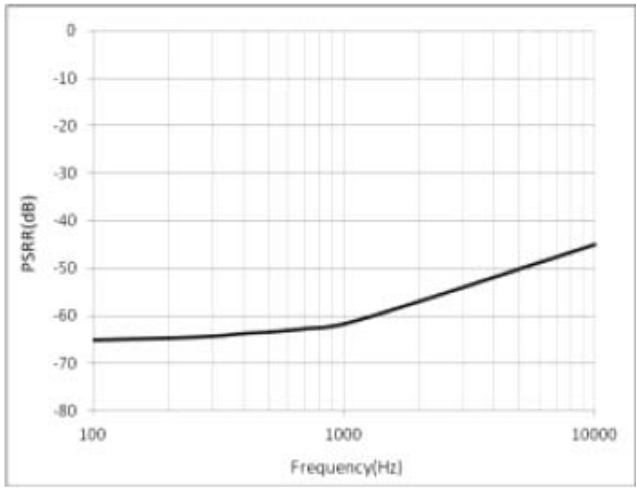
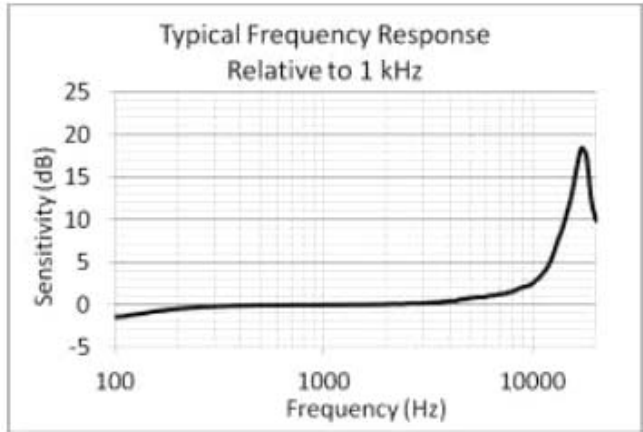
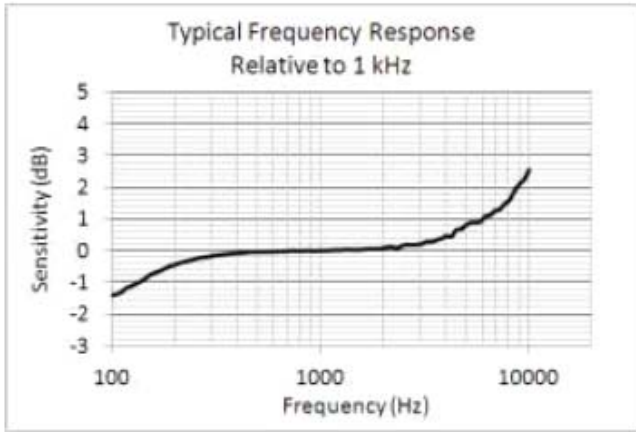
CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the

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operational sections of this specification is not implied.

Typical Performance Characteristics



TDMA Disturbance Immunity

- 75 dB Max @500 ~ 2500MHz ( Direct RF injection test according to set figure , this set figure is based on below block diagram. )

Instrument settings

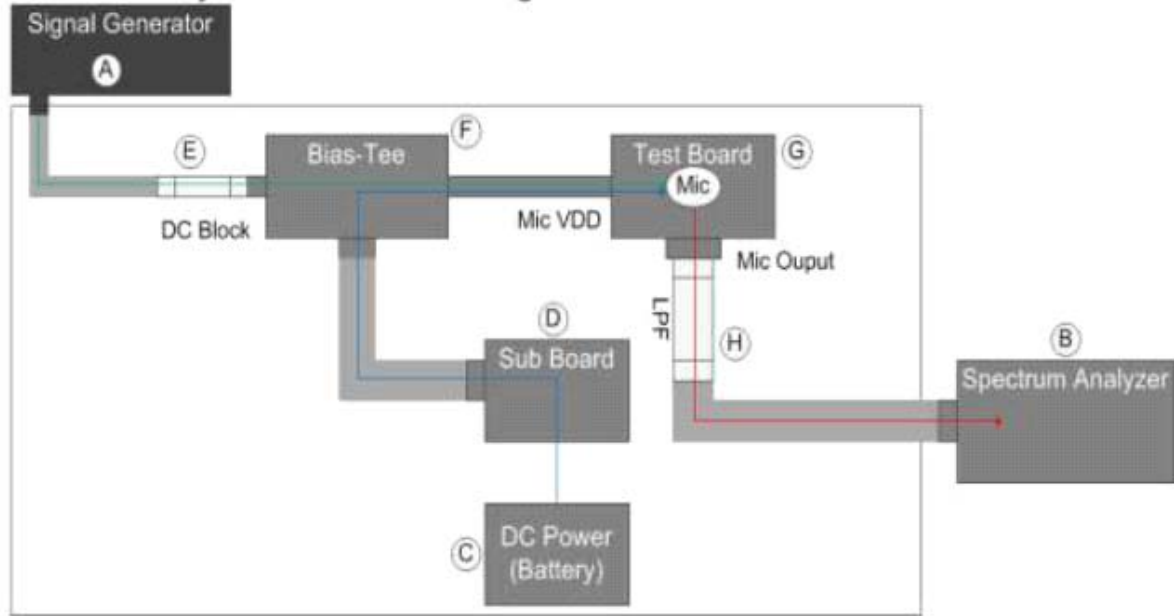
Signal Generator

- modulation: 1 kHz, AM, depth 80%

- test frequency and amplitude from frequency/amplitude table

MHz	dBm	MHz	dBm	MHz	dBm	MHz	dBm	MHz	dBm
100	-4.08	600	-2.85	1100	-1.64	1600	-0.52	2100	0.05
200	-3.68	700	-2.61	1200	-1.33	1700	-0.29	2200	0.12
300	-3.31	800	-2.39	1300	-1.25	1800	-0.11	2300	0.27
400	-3.24	900	-2.11	1400	-1.08	1900	-0.04	2400	0.31
500	-3.09	1000	-1.84	1500	-0.86	2000	-0.01	2500	0.45

### RF Immunity Measurement Diagram



A	Signal Generator	Rode & Schwarz SMIQ 03B
B	Spectrum Analyzer	Audio Precision APx525
C	DC Power	Battery 3V
D	Sub Board with RL & Capacitor	C: 0.1uF
E	DC block	Agilent 11742A
F	Bias-Tee	Mini-Circuits ZFBT-6GW
G	Test Board	ZTS6016 EVB
H	Low pass filter (Pass band 5M~2.5GHz)	Mini-Circuits SLP-2.5, SLP-5, SLP-150, SLP-450, SLP-1200, SLP-1650

### Reliability Tests

The microphone sensitivity after stress must deviate by no more than  $\pm 3\text{dB}$  from the initial value.

1.Heat Test, Operational	Temperature: $85\pm 3^{\circ}\text{C}$ Humidity: $85\pm 5\% \text{RH}$ Duration: 12 hours Voltage: Applied
2.Cold Test, Operational	Temperature: $-40\pm 3^{\circ}\text{C}$ Duration: 12 hours Voltage: Applied
3.Heat Test, Non-Operational	Temperature: $85\pm 3^{\circ}\text{C}$ Humidity: $50\pm 5\% \text{RH}$ Duration: 96 hours Voltage: Not Applied
4.Cold Test, Non-Operational	Temperature: $-40\pm 3^{\circ}\text{C}$ Duration: 96 hours Voltage: Not Applied
5.Condensation Test, Non-Operational	Temperature: $25\pm 3^{\circ}\text{C}$ and $55\pm 3^{\circ}\text{C}$ Humidity: $95\pm 5\% \text{RH}$ Duration: 1 hours each, during 10 minutes ramp, 45 cycles Voltage: Not applied
6.Temperature Cycling, Non-Operational	Temperature: $-40\pm 3^{\circ}\text{C}$ and $85\pm 3^{\circ}\text{C}$ Humidity: $50\pm 5\% \text{RH}$

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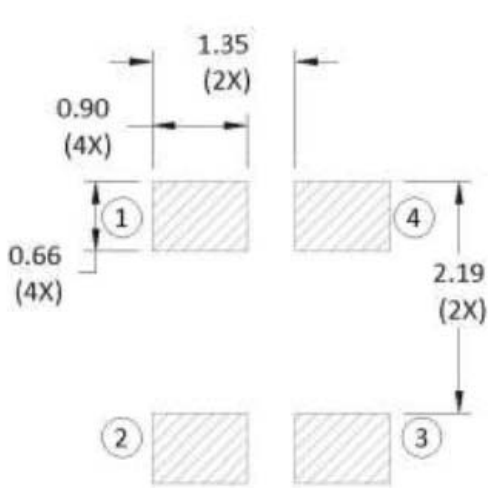
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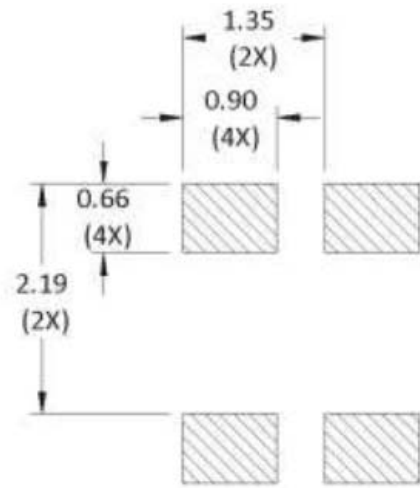
	Duration: 2 hours each, during 6 hours ramp, 5 cycles Voltage: Not applied
7.Thermal Shock Test, Non-Operational	Temperature: $-40\pm 3^{\circ}\text{C}$ and $85\pm 3^{\circ}\text{C}$ Duration: 30 minutes each, during 5 minutes ramp, 256 cycles Voltage: Not applied
8.Free Fall Test 1.5m	Placed inside test fixture and dropped on concrete from height 1.5m. (1)3 times by 6 surfaces (2)1 times by 12 edges (3)1 times by 8 corners
9.Random Vibration	Temperature: $23\pm 5^{\circ}\text{C}$ Humidity: 35~70% RH Duration: 2 hours each axis(X,Y,Z) Power Spectral Density: 5Hz $0.10\text{m}^2/\text{s}^3 (=1.0391*10^{-3}\text{g}^2/\text{Hz})$ 12Hz $2.20\text{m}^2/\text{s}^3 (=22.8602*10^{-3}\text{g}^2/\text{Hz})$ 20Hz $2.20\text{m}^2/\text{s}^3 (=22.8602*10^{-3}\text{g}^2/\text{Hz})$ 200Hz $0.04\text{m}^2/\text{s}^3 (=0.41534*10^{-3}\text{g}^2/\text{Hz})$ 200Hz $0.04\text{m}^2/\text{s}^3 (=0.41564*10^{-3}\text{g}^2/\text{Hz})$
10.Repeated Low Level Free Fall Test	Placed inside test fixture and dropped on rubber mat from height of 10cm. Each face 2500 times(Total 6 faces, 15000times)
11.1m Repeated Rotating Free Fall	Placed inside test fixture and dropped on steel sheet from height of 1.0m. 100 times(all faces) Rotation speed of barrel: 10~12 falls/minute
12.Free Fall Test for master box	Corner drop: Each Corner 1 time Edge drop: Each Edge 1 time Face drop: Each Face 1 time
13.Random Vibration for master box	Sinusoidal wave vibration Frequency: 5~50Hz Acceleration: $7.4\text{m}/\text{s}^2(0.76\text{G})$ Sweep speed: $9\text{Hz}/\text{min}(5\sim 50\text{Hz}, \text{one way } 5\text{ min})$ Test duration: Direction of Face 1-3 20min Direction of Face 2-4 20min Direction of Face 5-6 20min Sample and direction of vibration : 1 direction for 1 sample Package on vibrating table: Free
14.Substrate bending Test	Deflection: 3mm Rate: 0.5mm/sec
15.Adhesion	Load: 10 N Duration: 10 seconds
16.Electrostatic Discharge Test	Capacitance: 150pF Resistance: $330\Omega$ Duration: 10 times Air Discharge: Level 3(+/-8kV) Direct contact discharge: Level 1 (+/-2kV)
17.ESD-Human Body Model	3 discharges of $\pm 2\text{ kV}$ direct contact to I/O pins.(100pF,1500 $\Omega$ )
18.ESD-Charged Device Model	3 discharges of $\pm 500\text{V}$ direct contact to I/O pins.
19. ESD-Machine Mode	3 discharges of $\pm 200\text{ V}$ direct contact to I/O pins.
20.Self alignment effect	Displacement: 0.15mm

**Recommended Customer Land Pattern**

The recommended PCB land pattern for the HAT3125N4 should have a 1:1 ratio to the solder pads on the microphone package. Care should be taken to avoid applying solder paste to the sound hole in PCB. The dimensions of suggested solder paste pattern refer to the land pattern which should be shrunk by 0.025 per side.

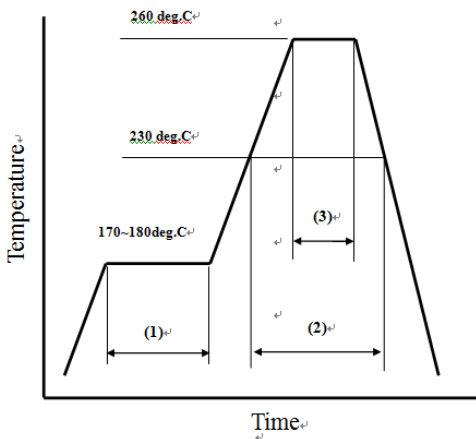


PCB Land Pattern Layout (Dimensions Shown in mm).



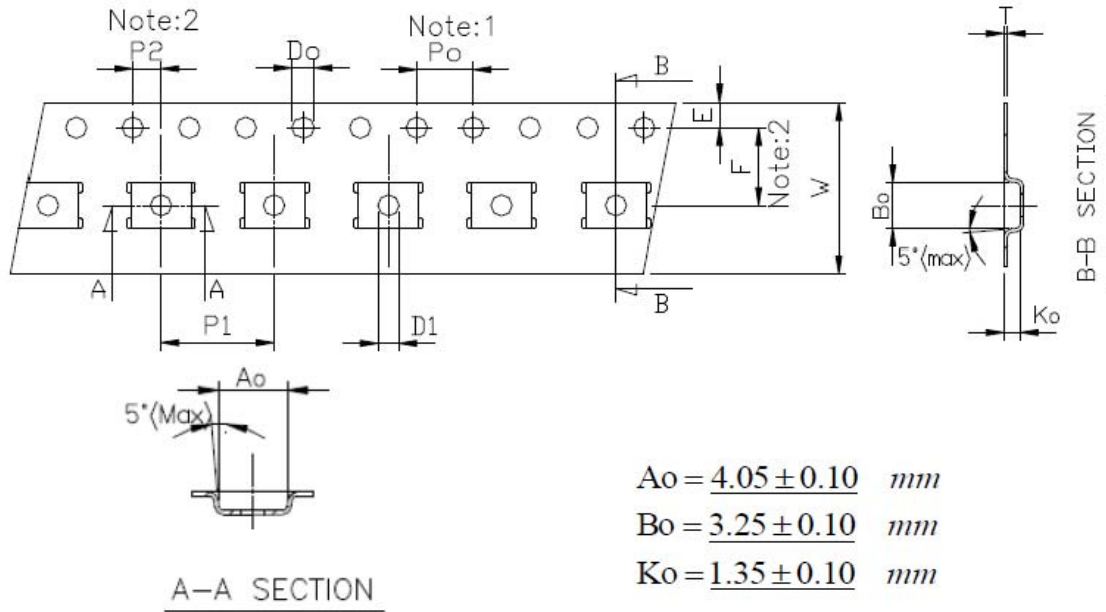
Suggested Solder Paste Stencil Pattern Layout.

**Solder Flow Profile**



Stage	Temperature Profile	Time (maximum)
Pre-heat	+170°C ~ +180°C	120sec
Primary heat	> +230°C	100sec
Peak	+260°C maximum	30sec

PACKAGING



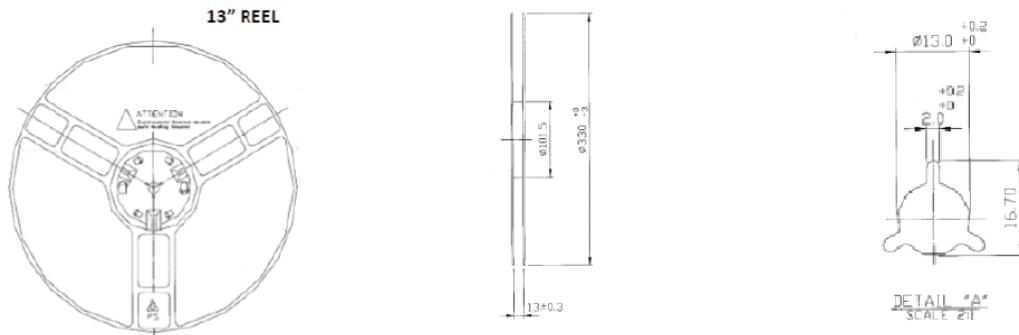
Unit : mm

Symbol	Spec
K1	-
Po	4.0 ± 0.10
P1	8.0 ± 0.10
P2	2.0 ± 0.05
Do	1.55 ± 0.05
D1	1.50 (MIN)
E	1.75 ± 0.10
F	5.50 ± 0.05
10Po	40.0 ± 0.10
W	12.0 ± 0.20
T	0.30 ± 0.05

Note

- 1 · 10 Sprocket hole pitch cumulative tolerance is ± 0.1mm.
- 2 · Pocket position relative to sprocket hole measured as true position of pocket not pocket hole.
- 3 · AO & BO measured on a plane 0.3mm above the bottom of the pocket to top surface of the carrier.
- 4 · KO measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
- 5 · Carrier camber shall be not that 1mm per 100mm through a length of 250mm.

Note: Dimensions are in millimeters unless otherwise specified.

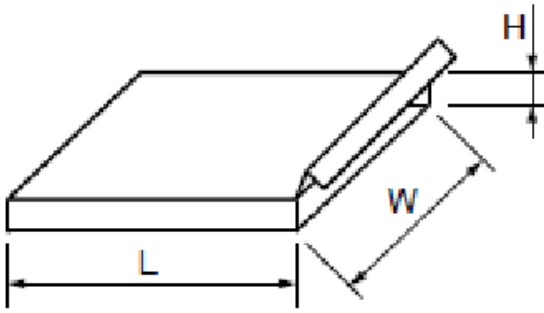


Part NO.	Reel Diameter	Quantity Per Reel	Quantity Per Inner Box	Quantity Per Outer Box
HAT3125N4	13"	5200	5200	46800

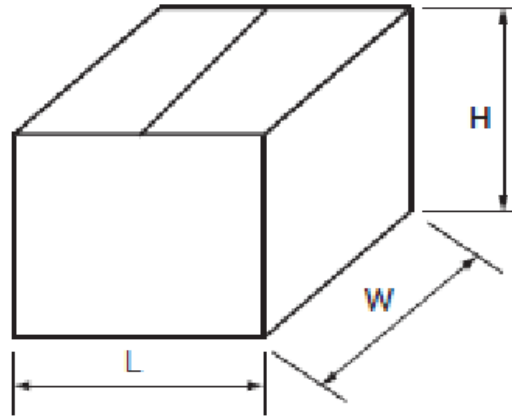
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Dimensions for Inner Box



Dimensions for Outer Box



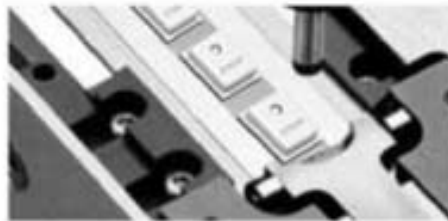
Unit : mm

L	W	H
335	339	45

Unit : mm

L	W	H
445	360	372

Pick and place guidelines of process



Rules of cleaning

Due to Clean the PCBA gap will make MEMS Mic. unit work improperly, please do not clean it by way of ultrasonic or use any cleaning solution to wash the soldered MEMS Mic. unit. If the PCB need to be cleaned, please seal with a tape on the both side of the acoustic hole to avoid foreign material and liquid invaded. MEMS Mic. is a electro-acoustic component which rely on its diaphragm vibrate in response to sound pressure, so that the sound pressure can be converted to electrical signals; Base on the above , If any cleaning liquid inject the Mic. unit, the vibrate spacing of the diaphragm would be constrained. As a result of that, if the diaphragm cannot vibrate well, it will make the output signal smaller or even no output.

Rules of the pressure of vacuum nozzle

If the Vacuum nozzle pressure is much more on the metal cap, it will directly affect the displacement of the diaphragm structure. When the displacement pressure is greater than the Max input sound pressure, the diaphragm will be damaged or cracked.

Note that Vacuum nozzle pressure cannot greater than 7PSI.

1K Pa = 0.145 pounds (lb / in2) = 0.0102 KGF / CM2 = 0.0098 atm.



### Rules of protection measurement

- 1 · Please do not let the vacuum nozzle suck the microphone acoustic hole.
- 2 · Do not vacuum the anti-static bag when repackaging the MEMS Mic.
- 3 · Do not blow the acoustic hole when cleaning the PCBA with air gun.

### Rules of the placement of vacuum nozzle

When pick and place the Mic. unit, the SMT Vacuum Tube should be placed in the center of the left and right sides of Mic. unit and keeps 0.5mm from the edge of the acoustic hole. This pick and place guidelines can apply to all series of HELE Top-Port MEMS Mic. products.

